

Precision Metals – NIC 3.0

Fingerstock and Custom Clip Opportunities

Laird leads the industry in Fingerstock and Custom Metal Clip design expertise and technologies. This is widely recognized in the marketplace and one of the reasons why Laird was chosen as a supplier for precision metal components in the Open Compute Project (OCP) – NIC 3.0.

The Open Compute Project (OCP) is a collaborative community focused on redesigning hardware technology to efficiently support the growing demands on compute infrastructure. Community partners include: Facebook, HP, Intel, AMD, Broadcom, Google, Huawei, Microsoft, LinkedIn, AT&T, Verizon, Nokia, etc.

One specific project that is being worked on by OCP is called NIC 3.0. NIC 3.0 specification defines a third-generation mechanical form factor that allows for interoperability between compliant baseboards and OCP NIC 3.0 cards. In addition, NIC 3.0 is addressing the limitations currently being experienced with NIC 2.0 such as board space, mechanical profile, connector placement, and specification quality. Two different form factor modules will be included in NIC 3.0, a small form factor (SFF) and a large form factor (LFF) – see Figures 1 and 2 for 4X SFP version examples. For additional NIC 3.0 information click this link:

[HTTPS://WWW.OPENCOMPUTE.ORG/WIKI/SERVER/MEZZ](https://www.opencompute.org/wiki/server/mezz)

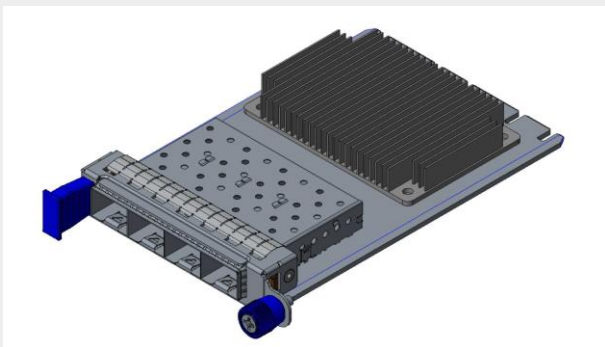


Figure 1 – NIC 3.0 SFF Module (4X SFP version)

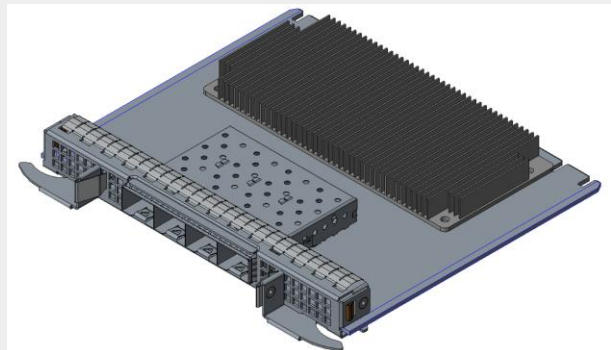


Figure 2 – NIC 3.0 LFF Module (4X SFP version)

The modules will include both fingerstock and side spring parts (Figure 3) and then the modules will get inserted into a chassis (Figure 4). Laird has worked with the OCP community to have Laird's part numbers stated in the NIC 3.0 specification so the large number of companies that will adopt to this specification can place orders directly with Laird for the parts.

The parts are in inventory at all the regional sampling centers for quick 24-hour turn on prototypes. Table 1 states the Laird part numbers by each module form factor type. In addition, hard tooling is already in place in Shenzhen to support larger quantity orders.

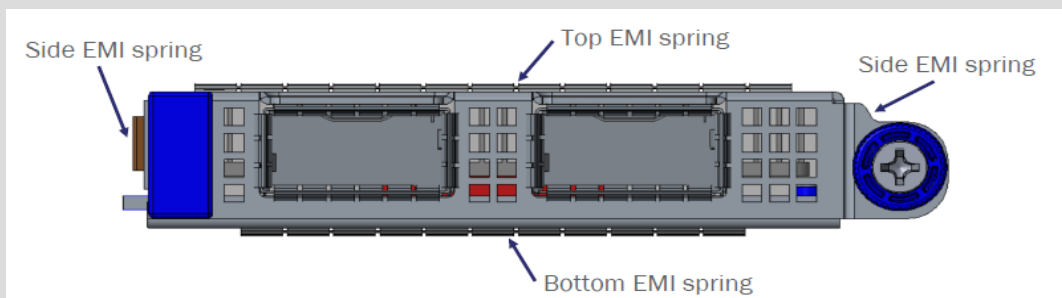


Figure 3 - Example of a 2X QSFP version module showing the location of the fingerstock and side springs.

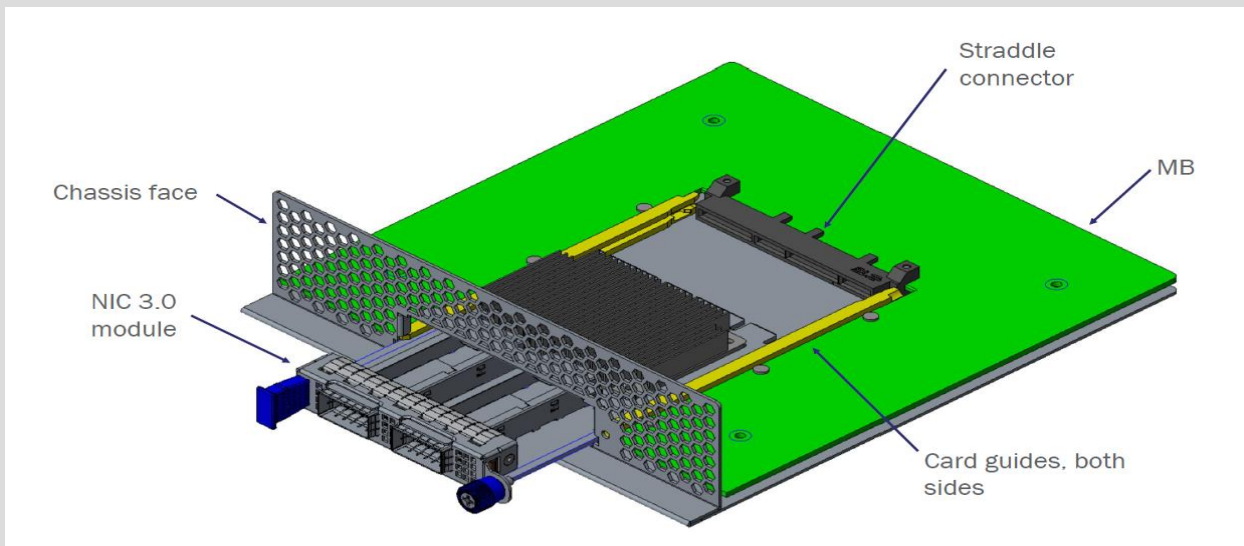


Figure 4 – NIC 3.0 module including chassis example

Laird Part Number	Description ⁽¹⁾	Module Form Factor	Qty Per
LT18CJ4430	Be/Cu Fingerstock – 9 fingers	SFF w/ Ejector Latch	1
LT18CJ1920	Be/Cu Fingerstock – 11 fingers	SFF w/ Internal Lock or Pull Tab	1
LT18CJ1921	Be/Cu Fingerstock – 13 fingers	SFF w/ Ejector Latch, Internal Lock, or Pull Tab	1
LT18DP1911	Be/Cu Side Clips	SFF w/ Ejector Latch, Internal Lock, or Pull Tab	2
LT18CJ1922	Be/Cu Fingerstock – 25 fingers	LFF w/ Ejector Latch	1
LT18CJ1923	Be/Cu Fingerstock – 27 fingers	LFF w/ Ejector Latch	1
LT18DP1911	Be/Cu Side Clips	LFF w/ Ejector Latch	2

Table 1 – Part Number List

(1): If Be-Free is a requirement, alternative materials such as Recyclable Clean Copper (RCC) are available for testing and evaluation.



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